S-8239A Series

Rev.1.3_00

OVERCURRENT MONITORING IC FOR MULTI-SERIAL-CELL PACK

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The S-8239A Series is an overcurrent monitoring IC for multi-serial-cell pack including high-accuracy voltage detection circuits and delay circuits.

The S-8239A Series is suitable for protection of lithium-ion / lithium polymer rechargeable battery packs from overcurrent.

Features

Built-in high-accuracy voltage detection circui	t	
Overcurrent 1 detection voltage ^{*1}	0.04 V to 0.30 V (10 mV step)	Accuracy ±15 mV
Overcurrent 2 detection voltage	0.1 V to 0.7 V (100 mV step)	Accuracy ±100 mV
Overcurrent 3 detection voltage	1.2 V (Fixed)	Accuracy ±300 mV
Built-in three-step overcurrent detection circul	t: Overcurrent 1, overcurrent 2, over	current 3
Overcurrent 3 detection function is selectable	: Available, unavailable	
 UVLO (under voltage lock out) function 		
UVLO detection voltage	2.0 V (Fixed)	Accuracy ±100 mV
 High-withstand voltage device is used: 	VM pin, DO pin: Absolute maximu	m rating 28 V
Delay times are generated only by an internal	circuit (External capacitors are unne	ecessary).
 Low current consumption 		
During normal operation:	7.0 μA max.	
During UVLO operation:	6.0 μA max.	
Output logic:	Active "L"	
 Wide operation temperature range: 	Ta = -40°C to +85°C	

- Lead-free (Sn 100%), halogen-free
- *1. Overcurrent 1 detection voltage \leq 0.06 V should be satisfied in the case of overcurrent 2 detection voltage = 0.1 V. Overcurrent 1 detection voltage $\leq 0.85 \times$ overcurrent 2 detection voltage -0.05 V should be satisfied in the case of overcurrent 2 detection voltage ≥ 0.2 V.

Applications

- Lithium-ion rechargeable battery pack
- Lithium polymer rechargeable battery pack

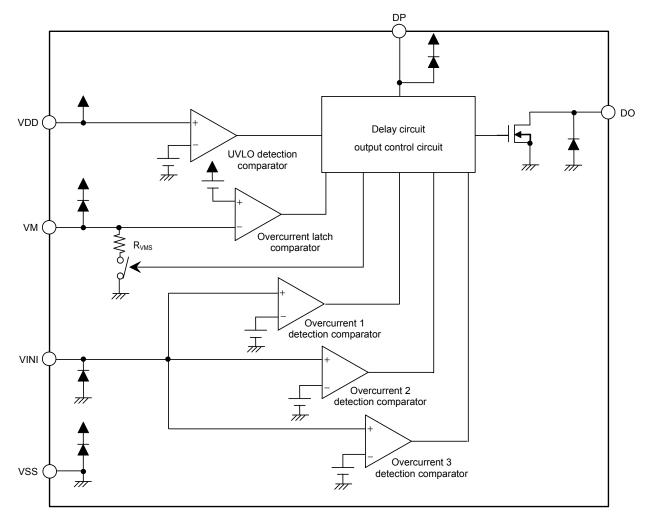
Package

• SOT-23-6

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Block Diagram

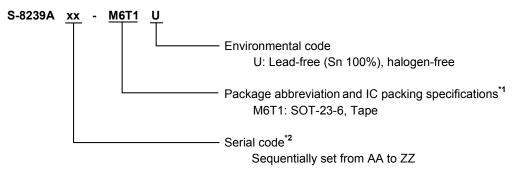


Remark All the diodes shown in the figure are parasitic diodes.

Figure 1

Product Name Structure

1. Product name



*1. Refer to the tape drawing.

*2. Refer to "3. Product name list".

2. Package

Table 1	Package	Drawing	Codes
10010 1	i uonugo	Draming	00000

Package Name	Dimension	Таре	Reel	
SOT-23-6	MP006-A-P-SD	MP006-A-C-SD	MP006-A-R-SD	

3. Product name list

Table 2

Product Name	Overcurrent 1 Detection Voltage [V _{DIOV1}]	Overcurrent 2 Detection Voltage [V _{DIOV2}]	Overcurrent 1 Detection Delay Time [t _{DIOV1}]	Overcurrent 2 Detection Delay Time [t _{DIOV2}]	Overcurrent 3 Detection Function
S-8239AAA-M6T1U	0.08 V	0.4 V	1150 ms	1.12 ms	Unavailable
S-8239AAB-M6T1U	0.10 V	0.5 V	1150 ms	0.28 ms	Unavailable
S-8239AAC-M6T1U	0.10 V	0.3 V	18.0 ms	0.28 ms	Unavailable
S-8239AAD-M6T1U	0.10 V	0.2 V	290 ms	0.56 ms	Unavailable
S-8239AAE-M6T1U	0.10 V	0.7 V	18.0 ms	0.56 ms	Unavailable
S-8239AAF-M6T1U	0.04 V	0.3 V	4600 ms	0.28 ms	Unavailable
S-8239AAG-M6T1U	0.10 V	0.2 V	1150 ms	1.12 ms	Available
S-8239AAH-M6T1U	0.06 V	0.1 V	290 ms	0.56 ms	Unavailable
S-8239AAI-M6T1U	0.10 V	0.3 V	290 ms	0.28 ms	Unavailable
S-8239AAJ-M6T1U	0.11 V	0.3 V	4600 ms	2.24 ms	Available

Remark Contact our sales office for the products with detection voltage value other than those specified above.

Pin Configuration

1. SOT-23-6

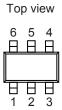


Figure 2

Pin No.	Symbol	Description
1	VINI	Voltage detection pin between VINI pin and VSS pin (Overcurrent detection pin)
2	VM	Overcurrent latch pin
3	DO	Connection pin of discharge control FET gate
4	DP ^{*1}	Test pin for delay time measurement
5	VDD	Input pin for positive power supply
6	VSS	Input pin for negative power supply

Table 3

*1. The DP pin should be open.

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Absolute Maximum Ratings

Table 4					
			(Ta = +25°C unless otherwise	specified)	
Item	Symbol	Applied pin	Absolute Maximum Rating	Unit	
Input voltage between VDD pin and VSS pin	V _{DS}	VDD	$V_{\rm SS}-0.3$ to $V_{\rm SS}$ +12	V	
VM pin input voltage	V _{VM}	VM	$V_{\text{DD}}-28$ to $V_{\text{DD}}+0.3$	V	
VINI pin input voltage	V _{VINI}	VINI	$V_{\rm SS}-0.3$ to $V_{\rm SS}+12$	V	
DO pin output voltage	V _{DO}	DO	$V_{\rm SS}-0.3$ to $V_{\rm SS}+28$	V	
Power dissipation	P _D	-	650 ^{*1}	mW	
Operation ambient temperature	T _{opr}	_	-40 to +85	°C	
Storage temperature	T _{stg}	_	–55 to +125	°C	

*1. When mounted on board

[Mounted board]

(1) Board size: $114.3 \text{ mm} \times 76.2 \text{ mm} \times t1.6 \text{ mm}$

(2) Board name: JEDEC STANDARD51-7

Caution 1. The DP pin should be open.

2. The absolute maximum ratings are rated values exceeding which the product could suffer physical damage. These values must therefore not be exceeded under any conditions.

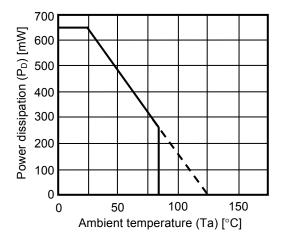


Figure 3 Power Dissipation of Package (When Mounted on Board)

Electrical Characteristics

1. Ta = +25°C

		Table 5		(Ta =	+25°С u	nless	otherwise s	pecified)
Item	Symbol	Condition	Min.	Тур.	Max.	Unit	Test Condition	Test
Detection Voltage						-		
Overcurrent 1 detection voltage	V _{DIOV1}	-	V _{DIOV1} - 0.015	V _{DIOV1}	V _{DIOV1} + 0.015	V	1	1
Overcurrent 2 detection voltage*1	V _{DIOV2}	_	V _{DIOV2} - 0.100	V _{DIOV2}	V _{DIOV2} + 0.100	V	1	1
Overcurrent 3 detection voltage	V _{DIOV3}	Overcurrent 3 detection function "available"	0.90	1.20	1.50	V	1	1
UVLO detection voltage	V_{UVLO}	_	1.90	2.00	2.10	V	1	1
Release Voltage								
Overcurrent release voltage	V_{RIOV}	V _{DD} criteria, V _{DD} = 3.5 V	0.7	1.2	1.5	V	1	1
Input Voltage, Operation Voltag	e							
Operation voltage between VDD pin and VSS pin	VDSOP	Output logic is determined ^{*2}	1.5	-	8	V	-	-
Current Consumption								
Current consumption during normal operation	I _{OPE}	V _{DD} = 3.5 V, V _{VM} = 0 V	1.0	3.5	7.0	μA	2	2
Current consumption during UVLO operation	I _{UVLO}	V _{DD} = V _{VM} = 1.5 V	0.7	3.0	6.0	μA	2	2
Internal Resistance								
Internal resistance between VM pin and VSS pin	R _{VMS}	$V_{DD} = V_{VM} = 3.5 V$	210	300	390	kΩ	3	3
Output Resistance								
DO pin resistance "L"	R _{DOL}	$V_{DD} = V_{VINI} = 3.5 V, V_{DO} = 0.5 V$	2.5	5	10	kΩ	4	4
Delay Time								
Overcurrent 1 detection delay time	t _{DIOV1}	_	$t_{\text{DIOV1}} \times 0.6$	t _{DIOV1}	$t_{\text{DIOV1}} \times 1.4$	ms	5	5
Overcurrent 2 detection delay time	t _{DIOV2}	_	$t_{\text{DIOV2}} \times 0.6$	t _{DIOV2}	$t_{\text{DIOV2}} \times 1.4$	ms	5	5
Overcurrent 3 detection delay time	t _{DIOV3}	Overcurrent 3 detection function "available"	168	280	392	μs	5	5
UVLO detection delay time	t _{UVLO}	_	2.94	4.90	6.86	s	5	5

*1. Even if overcurrent 1 detection voltage and overcurrent 2 detection voltage are in the same range, V_{DIOV1} is lower than V_{DIOV2}.

***2.** It indicates that DO pin output logic is determined.

OVERCURRENT MONITORING IC FOR MULTI-SERIAL-CELL PACK S-8239A Series

2. Ta = -40° C to $+85^{\circ}$ C^{*1}

Rev.1.3_00

		Table 6						
			(Ta = –4	0°C to -	⊦85°C ^{*1} ι	Inless	otherwise s	pecified
Item	Symbol	Condition	Min.	Тур.	Max.	Unit	Test Condition	Test Circuit
Detection Voltage	1			1	1		1	
Overcurrent 1 detection voltage	V _{DIOV1}	_	V _{DIOV1} - 0.021	V _{DIOV1}	V _{DIOV1} + 0.021	V	1	1
Overcurrent 2 detection voltage ^{*2}	V _{DIOV2}	-	V _{DIOV2} - 0.130	V_{DIOV2}	V _{DIOV2} + 0.130	V	1	1
Overcurrent 3 detection voltage	V _{DIOV3}	Overcurrent 3 detection function "available"	0.70	1.20	1.70	V	1	1
UVLO detection voltage	V _{UVLO}	—	1.85	2.00	2.15	V	1	1
Release Voltage							÷	
Overcurrent release voltage	V _{RIOV}	V _{DD} criteria, V _{DD} = 3.5 V	0.5	1.2	1.7	V	1	1
Input Voltage, Operation Voltag	е						÷	÷
Operation voltage between VDD pin and VSS pin	V _{DSOP}	Output logic is determined*3	1.5	-	8	V	-	-
Current Consumption								
Current consumption during normal operation	I _{OPE}	V_{DD} = 3.5 V, V_{VM} = 0 V	0.7	3.5	8.0	μA	2	2
Current consumption during UVLO operation	I _{UVLO}	V _{DD} = V _{VM} = 1.5 V	0.5	3.0	7.0	μA	2	2
Internal Resistance								
Internal resistance between VM pin and VSS pin	R _{VMS}	V _{DD} = V _{VM} = 3.5 V	150	300	450	kΩ	3	3
Output Resistance								
DO pin resistance "L"	R _{DOL}	$V_{DD} = V_{VINI} = 3.5 \text{ V}, V_{DO} = 0.5 \text{ V}$	1.2	5	15	kΩ	4	4
Delay Time								
Overcurrent 1 detection delay time	t _{DIOV1}	_	$t_{\text{DIOV1}} \times 0.2$	t _{DIOV1}	$t_{\text{DIOV1}} \times 1.8$	ms	5	5
Overcurrent 2 detection delay time	t _{DIOV2}	-	$t_{\text{DIOV2}} \times 0.2$	t _{DIOV2}	$t_{DIOV2} \times 1.8$	ms	5	5
Overcurrent 3 detection delay time	t _{DIOV3}	Overcurrent 3 detection function "available"	56	280	504	μs	5	5
	t _{UVLO}	_	0.98	4.90	8.82	s	5	5

*1. Since products are not screened at high and low temperatures, the specification for this temperature range is guaranteed by design, not tested in production.

*2. Even if overcurrent 1 detection voltage and overcurrent 2 detection voltage are in the same range, V_{DIOV1} is lower than V_{DIOV2} .

***3.** It indicates that DO pin output logic is determined.

Test Circuits

Caution Unless otherwise specified, the output voltage levels "H" and "L" at the DO pin (V_{DO}) are judged by the threshold voltage (1.0 V) of the N-channel FET. Judge the DO pin level with respect to V_{ss}.

Overcurrent 1 detection voltage, overcurrent 2 detection voltage, overcurrent release voltage, UVLO detection voltage (Test condition 1, test circuit 1)

The overcurrent 1 detection voltage (V_{DIOV1}) is defined as the voltage V2 whose delay time for changing V_{DO} from "H" to "L" lies between the minimum and the maximum value of the overcurrent 1 detection delay time after the voltage V2 is increased instantaneously (within 10 µs) from the set conditions of V1 = V3 = 3.5 V, V2 = 0 V.

The overcurrent 2 detection voltage (V_{DIOV2}) is defined as the voltage V2 whose delay time for changing V_{DO} from "H" to "L" lies between the minimum and the maximum value of the overcurrent 2 detection delay time after the voltage V2 is increased instantaneously (within 10 µs) from the set conditions of V1 = V3 = 3.5 V, V2 = 0 V.

The overcurrent release voltage (V_{RIOV}) is defined as the voltage V3 at which V_{DO} goes from "L" to "H" after decreasing V2 to 0 V and the voltage V3 is increased gradually from the set conditions of V1 = V2 = 3.5 V, V3 = 0 V.

The UVLO detection voltage (V_{UVLO}) is defined as the voltage V1 at which V_{DO} goes from "H" to "L" after the voltage V1 and V3 are decreased gradually from the set conditions of V1 = V3 = 3.5 V, V2 = 0 V.

2. Overcurrent 3 detection voltage (Overcurrent 3 detection function "available") (Test condition 1, test circuit 1)

The overcurrent 3 detection voltage (V_{DIOV3}) is defined as the voltage V2 whose delay time for changing V_{DO} from "H" to "L" lies between the minimum and the maximum value of the overcurrent 3 detection delay time after the voltage V2 is increased instantaneously (within 10 µs) from the set conditions of V1 = V3 = 3.5 V, V2 = 0 V.

3. Current consumption during normal operation, current consumption during UVLO operation (Test condition 2, test circuit 2)

The current consumption during normal operation (I_{OPE}) is the current that flows through the VDD pin (I_{DD}) under the set conditions of V1 = 3.5 V, V2 = 0 V.

The current consumption during UVLO operation (I_{UVLO}) is I_{DD} under the set conditions of V1 = V2 = 1.5 V.

4. Internal resistance between VM pin and VSS pin (Test condition 3, test circuit 3)

The internal resistance between the VM pin and the VSS pin (R_{VMS}) is the resistance between the VM pin and the VSS pin under the set condition of V1 = V2 = V3 = 3.5 V.

5. DO pin resistance "L" (Test condition 4, test circuit 4)

The DO pin resistance "L" (R_{DOL}) is the DO pin resistance under the set conditions of V1 = V2 = 3.5 V, V3 = 0.5 V.

6. Overcurrent 1 detection delay time (Test condition 5, test circuit 5)

6. 1 In the case of V_{DIOV2} = 0.1 V

The overcurrent 1 detection delay time (t_{DIOV1}) is the time period from when the voltage V2 exceeds V_{DIOV1} to when V_{DO} goes to "L", after V2 is increased to 0.08V instantaneously (within 10 µs) under the set conditions of V1 = 3.5 V, V2 = 0 V.

6. 2 In the case of $V_{\text{DIOV2}} \geq 0.2 \; \text{V}$

The overcurrent 1 detection delay time (t_{DIOV1}) is the time period from when the voltage V2 exceeds V_{DIOV1} to when V_{DO} goes to "L", after V2 is increased to V_{DIOV1} max. + 0.01 V instantaneously (within 10 µs) under the set conditions of V1 = 3.5 V, V2 = 0 V.

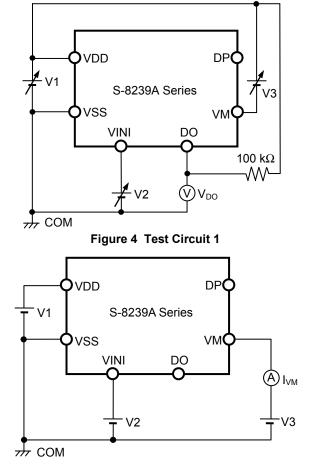
7. Overcurrent 2 detection delay time, UVLO detection delay time (Test condition 5, test circuit 5)

The overcurrent 2 detection delay time (t_{DIOV2}) is the time period from when the voltage V2 exceeds V_{DIOV2} to when V_{DO} goes to "L", after V2 is increased to 0.9 V instantaneously (within 10 µs) under the set conditions of V1 = 3.5 V, V2 = 0 V.

The UVLO detection delay time (t_{UVLO}) is the time period from when the voltage V1 falls below V_{UVLO} to when V_{DO} goes to "L", after V1 is decreased to 1.8 V instantaneously (within 10 µs) under the set conditions of V1 = 3.5 V, V2 = 0 V.

8. Overcurrent 3 detection delay time (Overcurrent 3 detection function "available") (Test condition 5, test circuit 5)

The overcurrent 3 detection delay time (t_{DIOV3}) is the time period from when the voltage V2 exceeds V_{DIOV3} to when V_{DO} goes to "L", after V2 is increased to 1.6 V instantaneously (within 10 µs) under the set conditions of V1 = 3.5 V, V2 = 0 V.



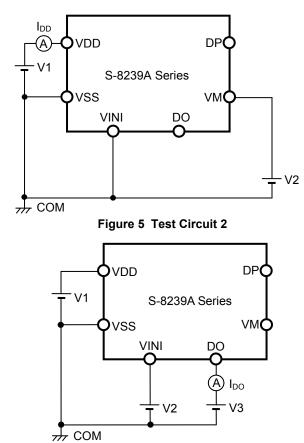


Figure 6 Test Circuit 3

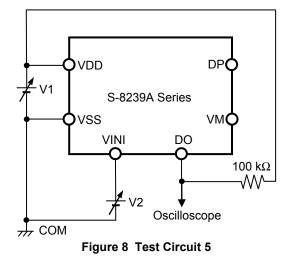


Figure 7 Test Circuit 4

Operation

1. Normal status

The S-8239A Series monitors the voltage between the VINI pin and the VSS pin to control discharging. When the VINI pin voltage is equal to or lower than the overcurrent 1 detection voltage (V_{DIOV1}), the DO pin becomes "High-Z". This status is called the normal status.

Caution When a battery is connected to the S-8239A Series for the first time, the DO pin may not be "High-Z". In this case, short the VM pin and VSS pin or connect the charger to restore the normal status.

2. Overcurrent status (Overcurrent 1, overcurrent 2, overcurrent 3)

When a battery is in the normal status, if the VINI pin voltage is equal to or higher than the overcurrent detection voltage because the discharge current is equal to or higher than the specified value and the status continues for the overcurrent detection delay time or longer, the DO pin voltage becomes the V_{SS} potential. This status is called the overcurrent status. The overcurrent status is retained when the voltage between the VDD pin and the VM pin is equal to or lower than the overcurrent release voltage (V_{RIOV}).

In the overcurrent status, the VM pin and VSS pin are shorted by the internal resistor between the VM pin and the VSS pin (R_{VMS}) in the S-8239A Series. However, the VM pin voltage is at the V_{DD} potential due to the external load as long as the external load is connected. When the external load is disconnected completely, the VM pin returns to the V_{SS} potential.

The overcurrent status is released when the voltage between the VDD pin and the VM pin is equal to or higher than V_{RIOV} .

3. UVLO status

The S-8239A Series includes a UVLO (under voltage lock out) function to prevent the IC malfunction due to the decrease of the battery voltage when detecting the overcurrent. When the battery voltage in the normal status is equal to or lower than the UVLO detection voltage (V_{UVLO}) and the status continues for the UVLO detection delay time (t_{UVLO}) or longer, the DO pin voltage becomes the V_{SS} potential. This status is called the UVLO status.

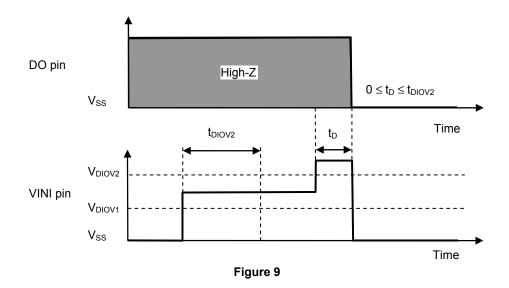
In the UVLO status, the VM pin and VSS pin are shorted by R_{VMS} between the VM pin and the VSS pin in the S-8239A Series.

After that, the UVLO status is released if the battery voltage becomes equal to or higher than V_{UVLO} .

4. Delay circuit

The detection delay times are determined by dividing a clock of approximately 3.5 kHz with the counter.

Remark The overcurrent 2 detection delay time (t_{DIOV2}) starts when the overcurrent 1 detection voltage (V_{DIOV1}) is detected. When the overcurrent 2 detection voltage (V_{DIOV2}) is detected over t_{DIOV2} after the detection of V_{DIOV1} , the DO pin becomes the V_{SS} potential within t_{DIOV2} of detection.



5. DP pin

The DP pin is a test pin for delay time measurement and it should be open in the actual application. If a capacitor whose capacitance is 1000 pF or more or a resistor whose resistance is 1 M Ω or less is connected to this pin, error may occur in the delay times or in the detection voltages.

■ Timing Chart

1. Overcurrent detection

1.1 Overcurrent 3 detection function "available"

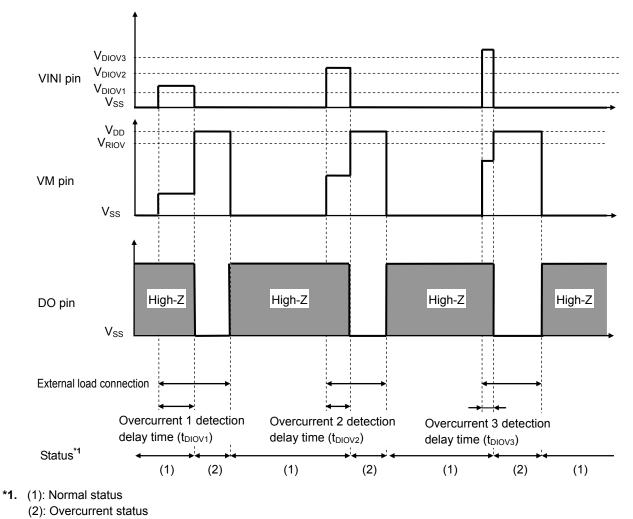


Figure 10

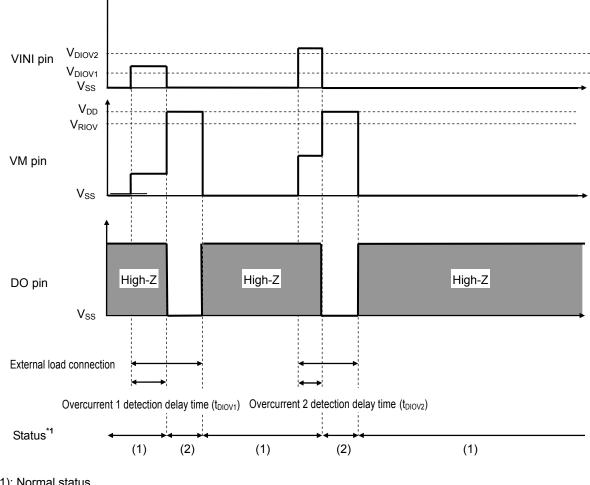


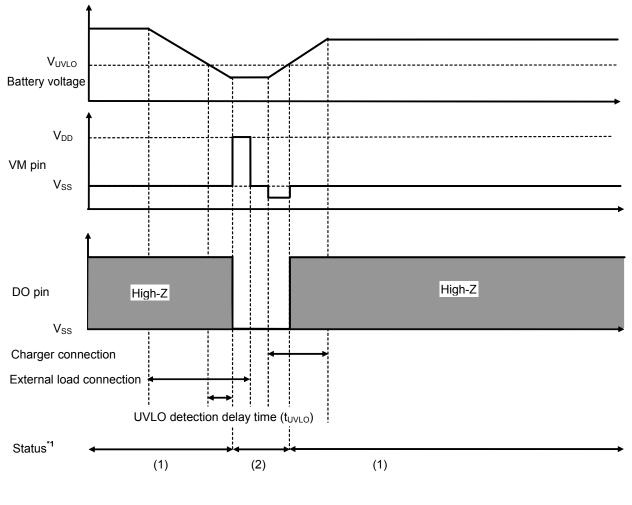
Figure 11

1.2 Overcurrent 3 detection function "unavailable"

*1. (1): Normal status(2): Overcurrent status

OVERCURRENT MONITORING IC FOR MULTI-SERIAL-CELL PACK S-8239A Series

2. UVLO detecion



*1. (1): Normal status

(2): UVLO status

Remark The charger is assumed to charge with a constant current.

Figure 12

■ 5-serial-cell Protection Circuit Example

Figure 13 shows the 5-serial-cell protection circuit example used by the S-8239A Series and the S-8225A Series. Contact our sales office when using the circuit other than the following protection circuit example.

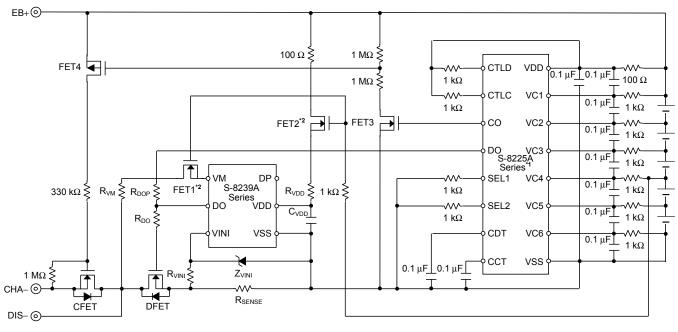


Figure 13

Table 7	Constants	for	External	Components
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Symbol	Min.	Тур.	Max.	Unit
R _{VDD}	300	470	1000	Ω
R _{VINI}	1	_	-	kΩ
R _{SENSE}	0	_	-	mΩ
R _{VM}	1	5.1	51	kΩ
R _{DO} *3	_	5.1	-	kΩ
R _{DOP}	330	510	2000	kΩ
C _{VDD}	0.022	0.1	1	μF

*1. Refer to the data sheet of the S-8225A Series for the recommended value for external components of the S-8225A Series.

- ***2.** Use the products with the same model number for FET1 and FET2.
- ***3.** Set up the optimal constant according to the FET in use.

Caution 1. The above constants may be changed without notice.

- 2. The example of connection shown above and the constants do not guarantee proper operation. Perform through evaluation using the actual application to set the constant.
- 3. The DP pin should be open.

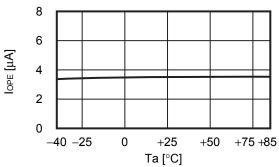
Precautions

- The application conditions for the input voltage, output voltage, and load current should not exceed the package power dissipation.
- Do not apply an electrostatic discharge to this IC that exceeds the performance ratings of the built-in electrostatic protection circuit.
- SII claims no responsibility for any and all disputes arising out of or in connection with any infringement by products including this IC of patents owned by a third party.

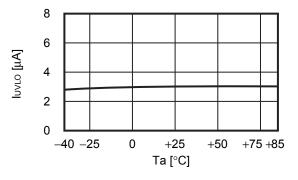
Characteristics (Typical Data)

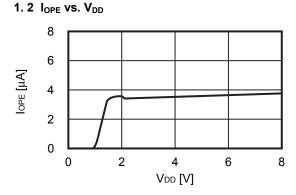
1. Current consumption





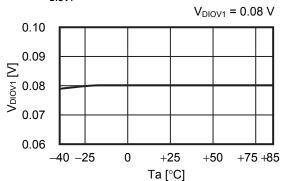


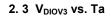


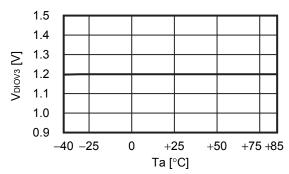


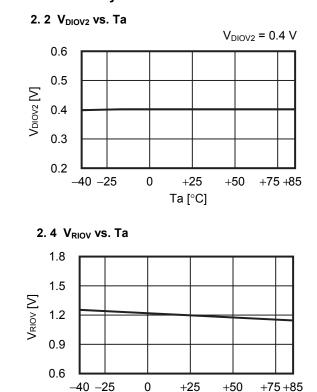
2. Overcurrent detection / release voltage, UVLO function and delay times

2.1 V_{DIOV1} vs. Ta

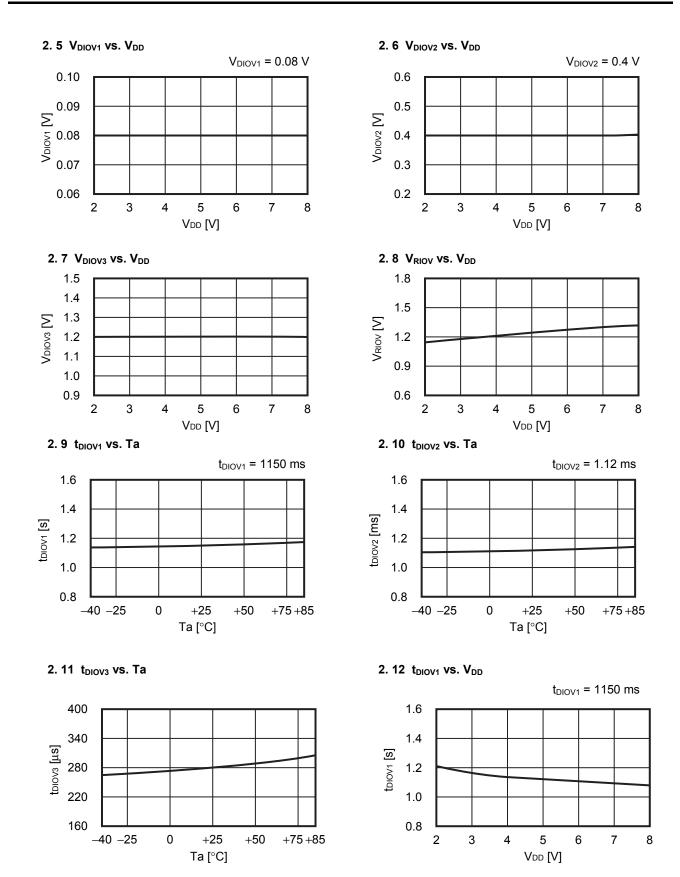


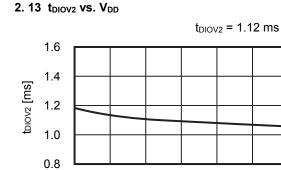






Ta [°C]





4

5

VDD [V]

6

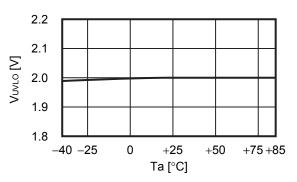
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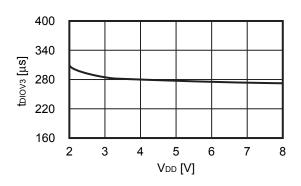
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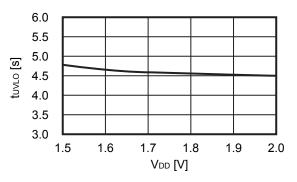
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2. 14 t_{DIOV3} vs. V_{DD}

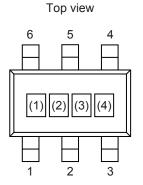






Marking Specification

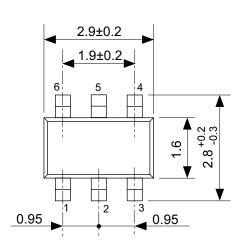
1. SOT-23-6

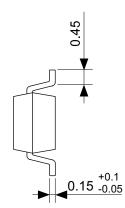


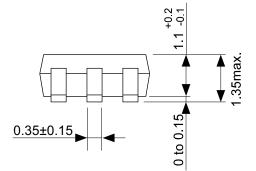
(1) to (3): (4): Product code (Refer to **Product name vs. Product code**) Lot number

Product name vs. Product code

Product Name	Product Code			
Troduct Name	(1)	(2)	(3)	
S-8239AAA-M6T1U	3	S	Α	
S-8239AAB-M6T1U	3	S	В	
S-8239AAC-M6T1U	3	S	С	
S-8239AAD-M6T1U	3	S	D	
S-8239AAE-M6T1U	3	S	Е	
S-8239AAF-M6T1U	3	S	F	
S-8239AAG-M6T1U	3	S	G	
S-8239AAH-M6T1U	3	S	Н	
S-8239AAI-M6T1U	3	S	Ι	
S-8239AAJ-M6T1U	3	S	J	

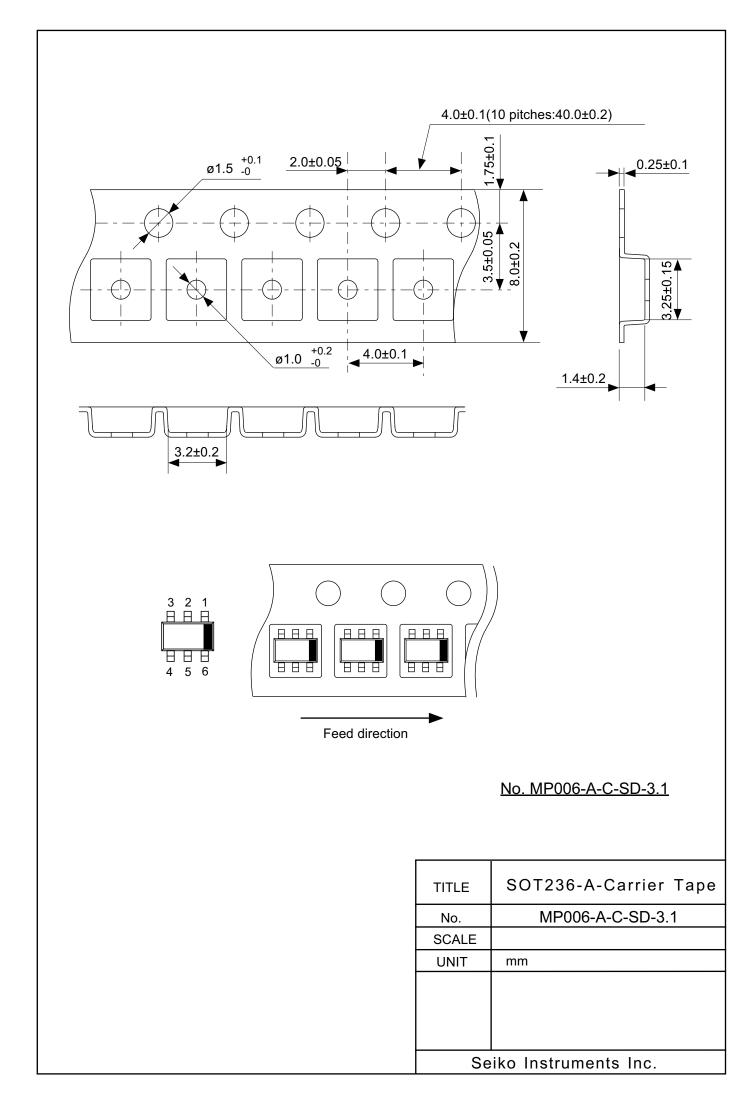


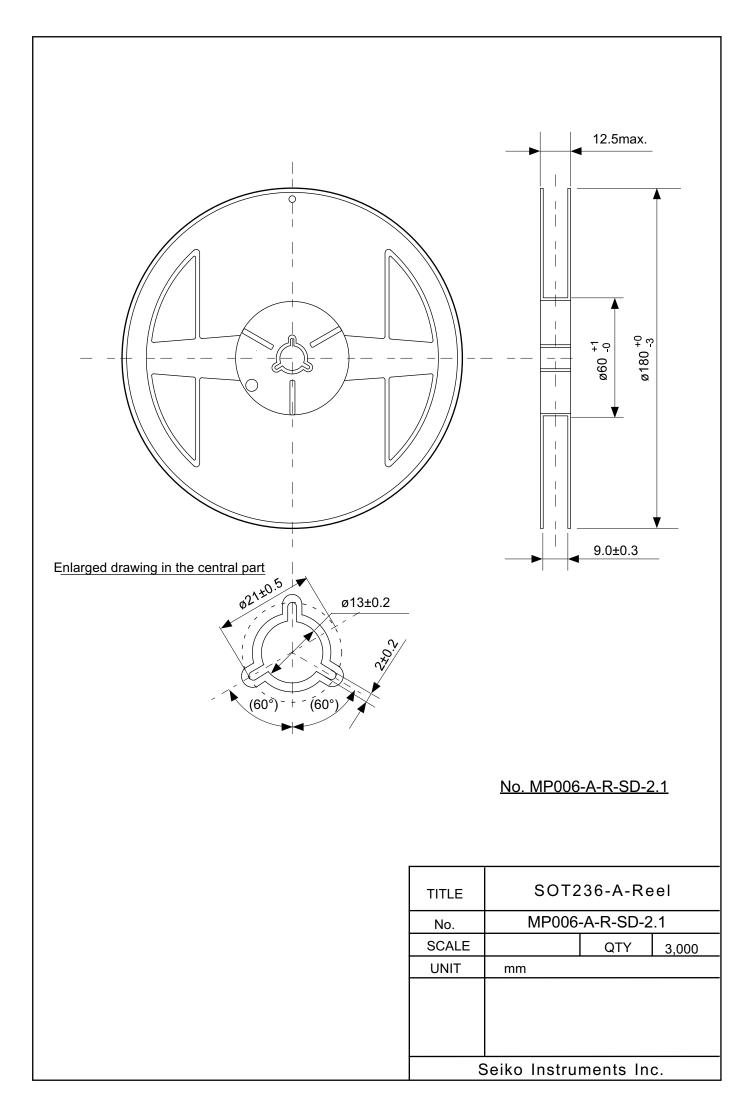




No. MP006-A-P-SD-2.0

TITLE	SOT236-A-PKG Dimensions			
No.	MP006-A-P-SD-2.0			
SCALE				
UNIT	mm			
Seiko Instruments Inc.				







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